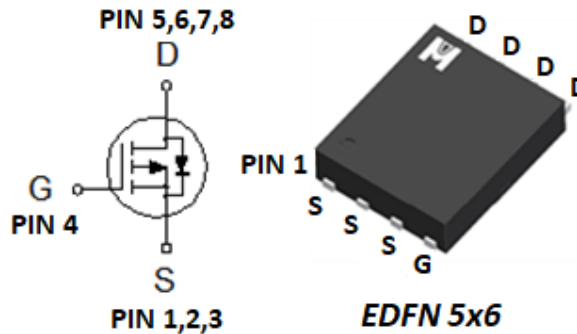


Single P-Channel Logic Level Enhancement Mode Field Effect Transistor

•Product Summary:

	P-CH
BV_{DSS}	-40V
$R_{DSON (MAX.) @ V_{GS} = -10V}$	14m Ω
$R_{DSON (MAX.) @ V_{GS} = -4.5V}$	22m Ω
$I_D @ T_C = 25^\circ C$	-45A

• Pin Description:



Single N Channel MOSFET

UIS, Rg 100% Tested

Pb-Free Lead Plating & Halogen Free



• ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNIT
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	I_D	$T_C = 25^\circ C$	-45
		$T_C = 100^\circ C$	-28
Pulsed Drain Current ¹	I_{DM}	-153	A
Avalanche Current ¹	I_{AS}	-50	
Avalanche Energy ¹	E_{AS}	L = 0.1mH	125
		E_{AR}	62.5
Repetitive Avalanche Energy ²			mJ
Power Dissipation ¹	P_D	$T_C = 25^\circ C$	50
		$T_C = 100^\circ C$	20
Operating Junction & Storage Temperature Range	T_j, T_{stg}	-55 to 150	$^\circ C$

• 100% UIS testing in condition of $V_D = -25V$, $L = 0.1mH$, $V_G = 10V$, $I_L = 25A$, Rated $V_{DS} = -40V$ P-CH

• THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	$R_{\theta JC}$		2.5	$^\circ C / W$
Junction-to-Ambient ³	$R_{\theta JA}$		50	

¹Pulse width limited by maximum junction temperature.

²Duty cycle $\leq 1\%$

³50 $^\circ C / W$ when mounted on a 1 in² pad of 2 oz copper.

▪ ELECTRICAL CHARACTERISTICS (T_J = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250uA	-40			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250uA	-1	-1.8	-3	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -32V, V _{GS} = 0V			-1	uA
		V _{DS} = -30V, V _{GS} = 0V, T _J = 125 °C			-25	
On-State Drain Current ¹	I _{D(ON)}	V _{DS} = -5V, V _{GS} = -10V	-45			A
Drain-Source On-State Resistance ¹	R _{DS(ON)}	V _{GS} = -10V, I _D = -20A		12	14	mΩ
		V _{GS} = -4.5V, I _D = -12A		18	22	
Forward Transconductance ¹	g _{fs}	V _{DS} = -5V, I _D = -20A		28		S
DYNAMIC						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = -20V, f = 1MHz		2479		pF
Output Capacitance	C _{oss}			274		
Reverse Transfer Capacitance	C _{rss}			204		
Gate Resistance	R _g	V _{GS} = -15mV, V _{DS} = 0V, f = 1MHz		2.9		Ω
Total Gate Charge ^{1,2}	Q _g (V _{GS} =10V)	V _{DS} = -20V, V _{GS} = -10V, I _D = -20A		45.0		nC
	Q _g (V _{GS} =4.5V)			23.3		
Gate-Source Charge ^{1,2}	Q _{gs}			6.1		
Gate-Drain Charge ^{1,2}	Q _{gd}			10.1		
Turn-On Delay Time ^{1,2}	t _{d(on)}	V _{DS} = -20V, V _{GS} = -10V, I _D = -1A, R _g = 6Ω		9		nS
Rise Time ^{1,2}	t _r			7		
Turn-Off Delay Time ^{1,2}	t _{d(off)}			78		
Fall Time ^{1,2}	t _f			39		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS						
Continuous Current	I _S				-45	A
Pulsed Current ³	I _{SM}				-153	
Forward Voltage ¹	V _{SD}	I _F = I _S , V _{GS} = 0V			-1.3	V
Reverse Recovery Time	t _{rr}	I _F = I _S , dI _F /dt = 100A / uS		17.5		nS
Peak Reverse Recovery Current	I _{RM(REC)}			1.28		A
Reverse Recovery Charge	Q _{rr}			11.3		nC

¹Pulse test : Pulse Width ≤ 300 usec, Duty Cycle ≤ 2%.

²Independent of operating temperature.

³Pulse width limited by maximum junction temperature.

EMC will review datasheet by quarter, and update new version.

▪ TYPICAL CHARACTERISTICS

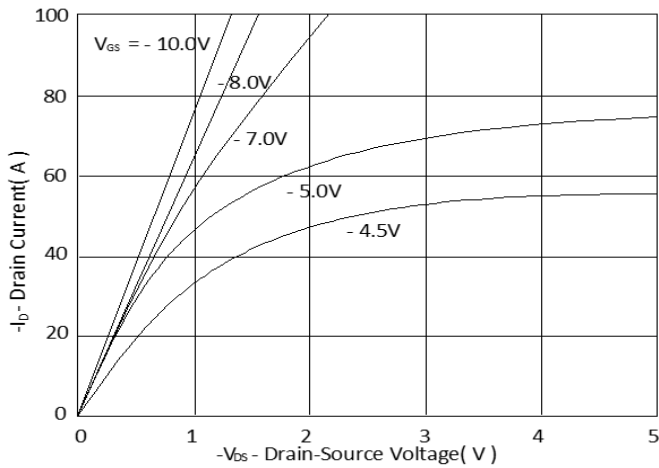


Fig.1 Typical Output Characteristics

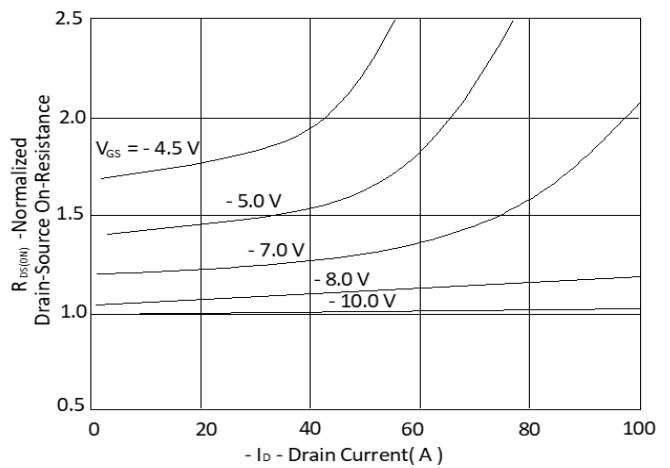


Fig.2 On-Resistance Variation with Drain Current and Gate Voltage

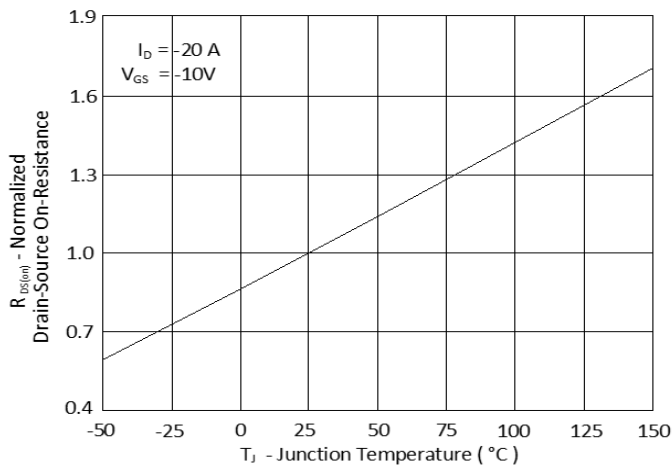


Fig.3 Normalized On-Resistance v.s. Junction Temperature

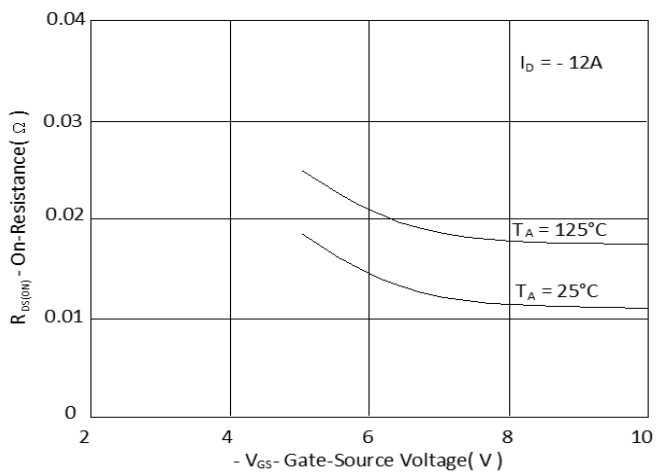


Fig.4 On-Resistance v.s. Gate Voltage

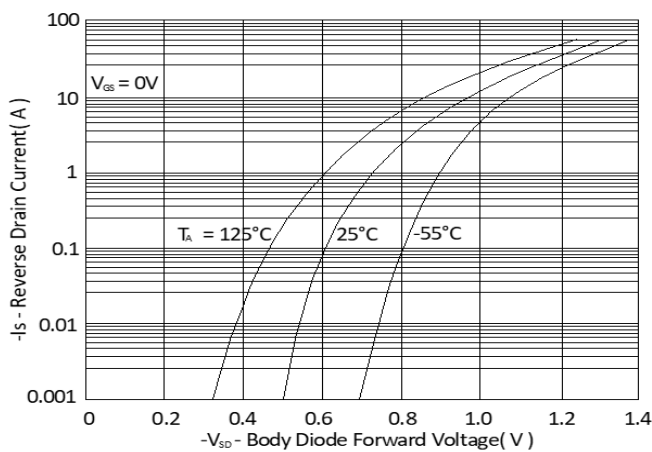


Fig.5 Forward Characteristic of Reverse Diode

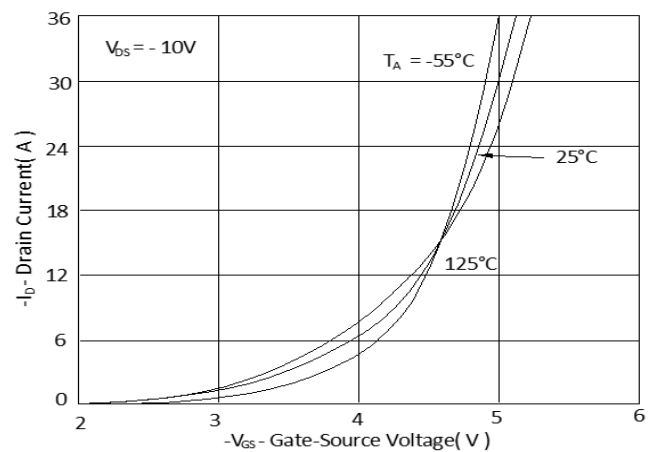


Fig.6 Transfer Characteristics

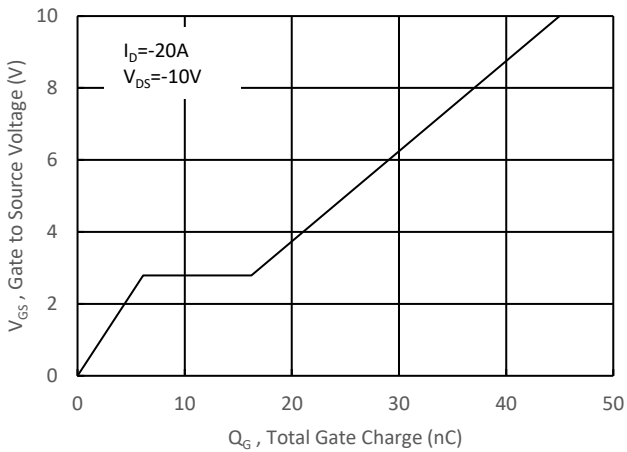


Fig.7 Gate Charge Characteristics

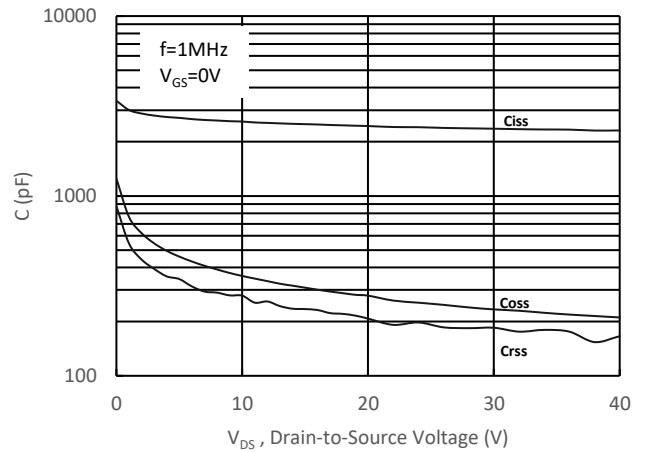


Fig.8 Typical Capacitance Characteristics

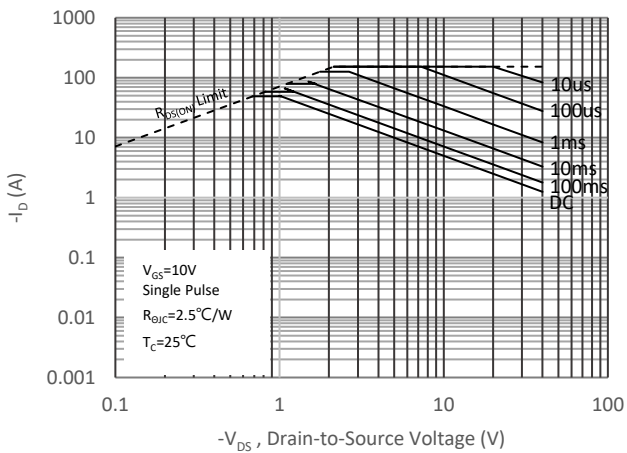


Fig.9. Maximum Safe Operating Area

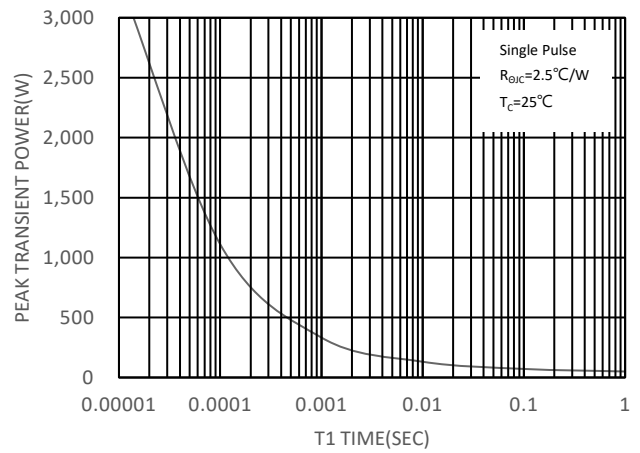


Fig.10. Single Pulse Maximum Power Dissipation

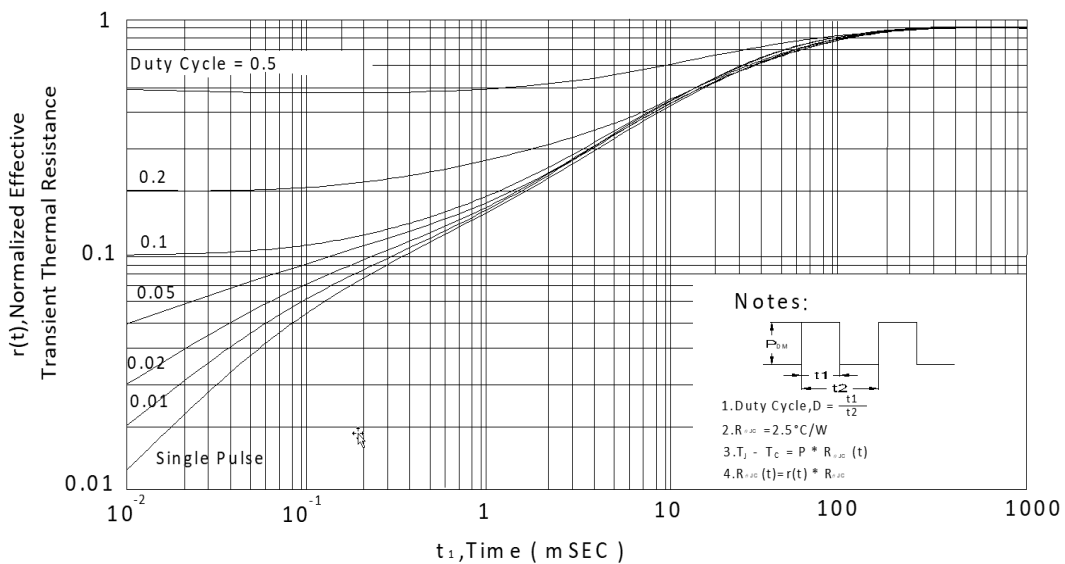
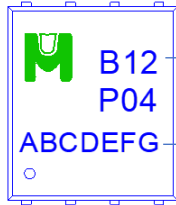


Fig.11. Effective Transient Thermal Impedance

Ordering & Marking Information:

Device Name: EMB12P04H for EDFN 5x6



B12P04: Device Name

ABCDEFGH: Date Code

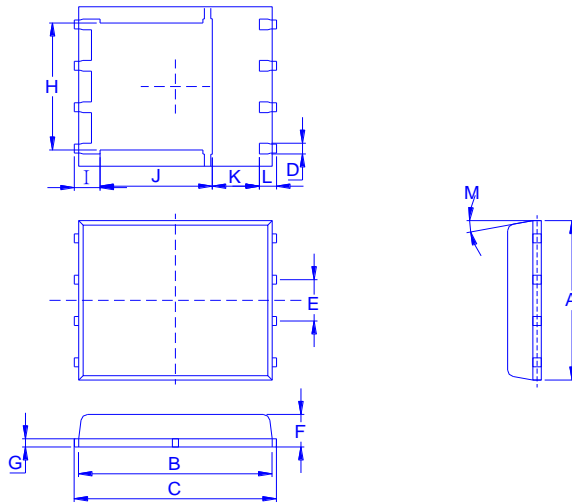
A: Assembly House

B: Year(A:2008 B:2009 C:2010....)

C: Month(A:01 B:02 C:03 D:04 E:05 F:06 G:07 H:08 I:09 J:10 K:11 L:12)

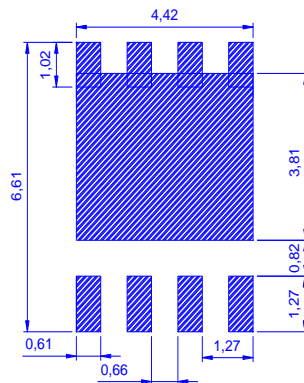
DEFG: Serial No.

Outline Drawing

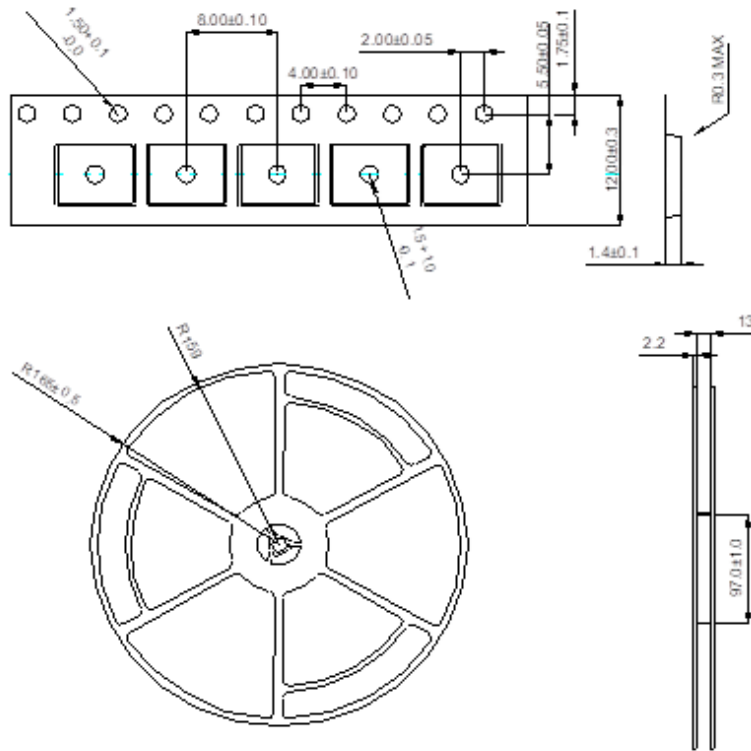


Dimension	A	B	C	D	E	F	G	H	I	J	K	L	M
Min	4.8	5.55	5.9	0.3	1.17	0.85	0.15	3.61	0.38	3.18	1	0.38	0°
Typ.	4.9	5.7	6	0.4	1.27	0.95	0.2	3.87	0.4	3.44	1.2	0.4	
Max	5.4	5.85	6.15	0.51	1.37	1.17	0.34	4.31	0.71	3.78	1.39	0.71	12°

Footprint



◆ Tape&Reel Information:2500pcs/Reel(Dimension in millimeter)



產品別	EDFN 5x6
Reel尺寸	13"
編帶方式	<p>FEED DIRECTION</p>
前空格	25
後空格	50
裝箱數	
滿捲數量	2.5K
捲/內盒比	01:01
內盒滿箱數	2.5K
內/外箱比	10:01
外箱滿箱數	25K